

Topical Issue in High Temperature Materials and Processes: The 3rd International Conference on Materials, Manufacturing Processes and Devices

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The 3rd International Conference on Materials, Manufacturing Processes and Devices" was co-organized by Jiangsu University of Science and Technology (JUST), China and the University of Auckland, New Zealand. It was successfully held at JUST in Zhenjiang, China on October 13-16, 2023. This conference attracted well-known experts and scholars to give special reports to communicate with experienced material scientists and industrial technologists. A wide range of topics were discussed at the conference, including nano-materials and nanotechnology, high temperature materials, Energy Storage Materials, advanced manufacturing processes and innovative metallic, ceramic, composite materials, and so on. We believe that by providing these opportunities, our young scientists and engineers have learned a lot from the fast-developing materials world.

TOPIC AND SCOPE

Topic:

Advanced Materials and Processing Technologies

Scope of the Issue:

Advanced materials joining technology, advanced surface technology, advanced energy materials, advanced materials in metallic and ceramic, computational materials and simulations, advanced manufacturing processes.

HOW TO SUBMIT

Deadline: May 15th 2024

Estimated number of manuscripts: around 35 papers

Before submission authors should carefully read the [Instruction for Authors](#). In order to make the preparation of manuscript easier, you are advised to use the [Manuscript Template](#).

All submissions to the Topical Issue must be made electronically via the [Editorial Manager submission and tracking review system](#). When entering your submission via the online submission system please choose "TopicalIssue_Conference on Materials, Manufacturing Processes and Devices".

All manuscripts will undergo the standard peer-review process (single-blind, at least two independent reviewers). When entering your submission via online submission system please choose "Topical Issue: The 3rd International Conference on Materials, Manufacturing Processes and Devices".

The deadline for submissions is May 15th 2024, but individual papers will be reviewed and published online on an ongoing basis.

Participants of The 3rd International Conference on Materials, Manufacturing Processes and Devices can obtain a 50% discount on an APC fee.

In case of any question please contact Ms. Joanna Kosińska, Managing Editor of High Temperature Materials and Processes, Joanna.Kosinska@degruyter.com